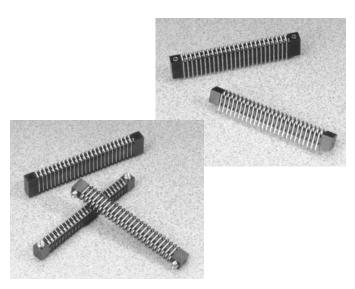
.050" (1.27mm) Series 501 & 503 Compression/Stacking Connector





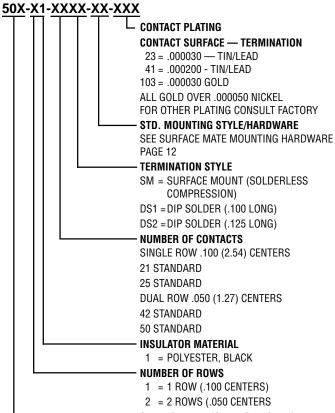
Features and Benefits

- Combine board standoff function with parallel board interconnect function
- Connects two or more stacked/surface mount boards
- Optional polarizing mounting hardware is available (threaded and thru-hole)
- Various contact platings are available
- Optional board stiffeners are recommended in some applications

Specifications

■ See general specifications page 3

PART NUMBER CODING



SURFACE MATE (SURFACE MOUNT)

501 = .325 HIGH INSULATOR 503 = .538 HIGH INSULATOR

(CONSULT FACTORY FOR AVAILABILITY OF ADDITIONAL INSULATOR HEIGHTS)

Board Stiffeners



Features & Benefits

- Board stiffeners are recommended when assembling PCBs less than .062 thick
- Molded of glass filled PPS for strength and stability
- Temperature rated up to 150°C
- Available in 42 and 50 positions
- Metal Stiffeners are offered. Consult factory for availability

*Used with 500, 501 and 503 Series

PART NUMBER CODING

186-1269-XX

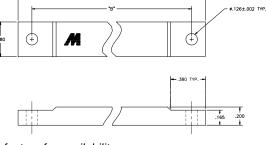
 CONTACT
 "A"
 "B"

 42
 2.650
 2.350

 50
 3.050
 2.750

DIMENSIONS

MATERIAL: POLYPHENYLENE SULFIDE (94 V-0) BLACK



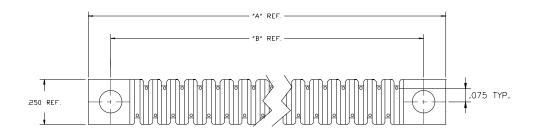
*Consult factory for availability

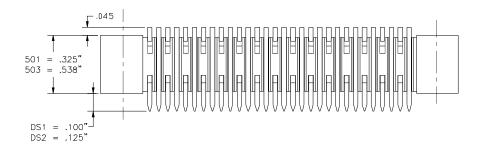


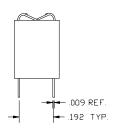
1700 Hicks Road • Rolling Meadows, IL 60008 USA Telephone: 847.392.3500 • Fax: 847.392.9404 email: mcpsales@methode.com • Web Page: www.methode.com

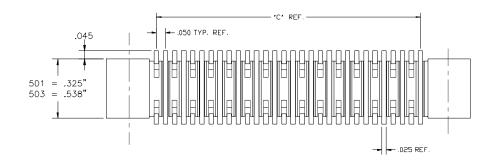
.050" (1.27mm) Series 501 & 503 Compression/Stacking Connector

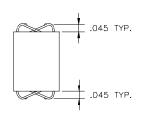


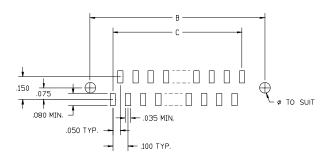












RECOMMENDED PAD LAYOUT SURFACE MOUNT (SOLDERLESS COMPRESSION)

RECOMMENDED PIN LAYOUT DIP SOLDER

DIMENSIONS			
SIZE	Α	В	C
46	2.600	2.350	2.050
50	3.000	2.750	2.450